

# N-Channel Enhancement Mode MOSFET

### **Description**

The IRLML0040TRPBF uses advanced trench technology

to provide excellent R<sub>DS(ON)</sub>, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

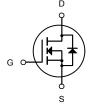


### **General Features**

 $V_{DS} = 40V I_{D} = 5A$ 

 $R_{DS(ON)} < 38m\Omega$  @  $V_{GS}=10V$ 

 $R_{DS(ON)} < 52m\Omega$  @  $V_{GS}=4.5V$ 



#### N-Channel MOSFET

## **Application**

Battery protection

Load switch

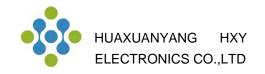
Uninterruptible power supply

## **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
IRLML0040TRPBF	SOT-23	2318	3000

### Absolute Maximum Ratings (T<sub>C</sub>=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	40	V
Vgs	Gate-Source Voltage	±12	V
	Drain Current – Continuous (T <sub>C</sub> =25°C)	5	Α
lσ	Drain Current – Continuous (Tc=70 °C)	4.2	Α
P <sub>D</sub>	Power Dissipation (Tc=25°C)	1.56	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θ</sub> JA	Thermal Resistance Junction to ambient	80	°C/W



Symbol	Parameter	Condition	Min	Тур	Max	Unit	
Static Electrical Characteristics @ T <sub>J</sub> = 25°C (unless otherwise stated)							
$V_{\text{(BR)DSS}}$	Drain-Source Breakdown Voltage	Vgs=0V ID=250μA	40			V	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>A</sub> =25°C)	V <sub>D</sub> S=40V, V <sub>G</sub> S=0V			1	μA	
	Zero Gate Voltage Drain Current(T <sub>A</sub> =125℃)	VDS=40V, VGS=0V			100	uA	
I <sub>GSS</sub>	Gate-Body Leakage Current	Vgs=±20V, Vps=0V			±100	nA	
$V_{\rm GS(TH)}$	Gate Threshold Voltage	VDS=VGS, ID=250μA	0.7	1.2	2.0	٧	
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance②	Vgs=10V, ID=5A		30	38	mΩ	
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance②	Vgs=4.5V, ID=4A		36	52	mΩ	
Dynamic	Electrical Characteristics @ T <sub>J</sub> = 25°C (ι	unless otherwise state	d)				
C <sub>iss</sub>	Input Capacitance			340		pF	
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1MHz		60		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			30		pF	
$R_g$	Gate Resistance	f=1MHz		7.8		Ω	
$Q_g$	Total Gate Charge	V <sub>DS</sub> =20V		5.8		nC	
$Q_{gs}$	Gate Source Charge	ID=5A,		0.4		nC	
$Q_{gd}$	Gate Drain Charge	Vgs=10V		2		nC	
Switching	Characteristics @ T <sub>J</sub> = 25°C (unless ot	herwise stated)					
t <sub>d(on)</sub>	Turn on Delay Time			4.1		ns	
t <sub>r</sub>	Turn on Rise Time	V <sub>DD</sub> =20V, I <sub>D</sub> =3.5A,		11.6		ns	
$t_{d(off)}$	Turn Off Delay Time	Rg=1Ω, Vgs=4.5V	-	24		ns	
t <sub>f</sub>	Turn Off Fall Time			7.6		ns	
Source Di	rain Diode Characteristics @ T <sub>J</sub> = 25°C (	unless otherwise state	ed)				
I <sub>SD</sub>	Source drain current(Body Diode)	T <sub>A</sub> =25℃			1.75	А	
V <sub>SD</sub>	Forward on voltage②	Tj=25°C, IsD=3.5A, VGS=0V		0.79	1.2	V	

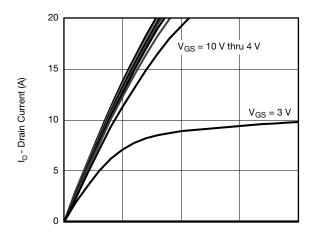
#### Notes:

 $<sup>\</sup>ensuremath{\textcircled{1}}$  Pulse width limited by maximum allowable junction temperature

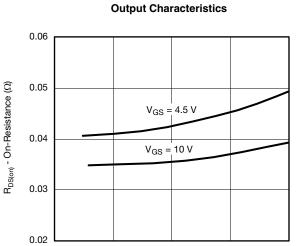
②Pulse test ; Pulse width≤300μs, duty cycle≤2%.



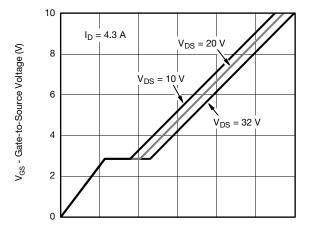
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



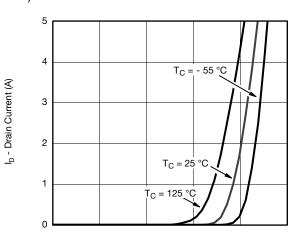
V<sub>DS</sub> - Drain-to-Source Voltage (V)



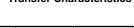
 $\label{eq:local_power} \mathbf{I_D} \text{ - Drain Current (A)}$  On-Resistance vs. Drain Current and Gate Voltage

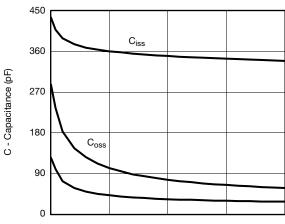


 $\mathbf{Q}_{\mathrm{g}}$  - Total Gate Charge (nC)  $\mathbf{Gate\ Charge}$ 



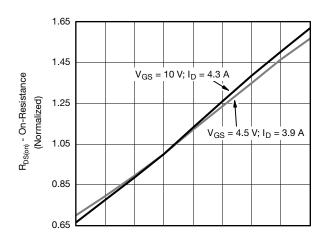
V<sub>GS</sub> - Gate-to-Source Voltage (V) **Transfer Characteristics** 





 $V_{DS}$  - Drain-to-Source Voltage (V)

#### Capacitance

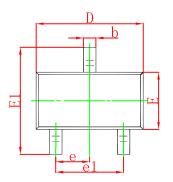


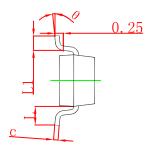
T<sub>J</sub> - Junction Temperature (°C)

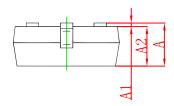
On-Resistance vs. Junction Temperature



# **SOT-23 Package Outline Dimensions**

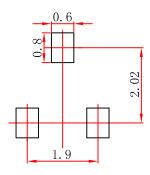






Cymphol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# **SOT-23 Suggested Pad Layout**



### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
  3.The pad layout is for reference purposes only.

## IRLML0040TRPBF

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